



(11) **EP 1 424 719 B9**

(12) **CORRECTED EUROPEAN PATENT SPECIFICATION**

Note: Bibliography reflects the latest situation

(15) Correction information:
Corrected version no 1 (W1 B1)
Corrections, see
Description Paragraph(s) 61, 62, 64-68, 71,
72, 74, 76

(51) Int Cl.:
H01J 17/16^(2006.01) **H01J 17/49^(2006.01)**
H01J 9/24^(2006.01)

(48) Corrigendum issued on:
02.01.2008 Bulletin 2008/01

(45) Date of publication and mention
of the grant of the patent:
25.07.2007 Bulletin 2007/30

(21) Application number: **03027419.5**

(22) Date of filing: **27.11.2003**

(54) **Display panel and method of manufacturing the display panel**

Anzeigetafel und Verfahren zur Herstellung der Anzeigetafel

Panneau d'affichage et procédé de fabrication du panneau d'affichage

(84) Designated Contracting States:
DE FR GB

(30) Priority: **28.11.2002 JP 2002345727**

(43) Date of publication of application:
02.06.2004 Bulletin 2004/23

(73) Proprietor: **Pioneer Corporation**
Meguro-ku,
Tokyo (JP)

(72) Inventors:
• **Yoshinari, Masaki**
Nakakoma-gun
Yamanashi-ken 409-3843 (JP)

• **Akiyama, Kazuya**
Nakakoma-gun
Yamanashi-ken 409-3843 (JP)

(74) Representative: **Sajda, Wolf E. et al**
MEISSNER, BOLTE & PARTNER
Widenmayerstrasse 48
80538 München (DE)

(56) References cited:
EP-A- 0 448 727

• **PATENT ABSTRACTS OF JAPAN vol. 2000, no.**
07, 29 September 2000 (2000-09-29) & JP 2000
100335 A (HITACHI METALS LTD), 7 April 2000
(2000-04-07)

EP 1 424 719 B9

Note: Within nine months from the publication of the mention of the grant of the European patent, any person may give notice to the European Patent Office of opposition to the European patent granted. Notice of opposition shall be filed in a written reasoned statement. It shall not be deemed to have been filed until the opposition fee has been paid. (Art. 99(1) European Patent Convention).

Description

BACKGROUND OF THE INVENTION

[0001] This invention relates to a display panel having a hermetically sealed space formed between two substrates, a method of manufacturing the display panel, and a partition wall included in the display panel.

[0002] The present application claims priority from Japanese Application No. 2002-345727.

[0003] Display panels used in display apparatuses include a flat display panel designed to have a hermetically sealed space formed between two substrates, such as a plasma display panel (hereinafter referred to as "PDP") and a field emission display panel (hereinafter referred to as "FED").

[0004] Fig. 1 is a schematic front view illustrating the cell structure of a conventional PDP. Fig. 2 is a sectional view taken along the V-V line in Fig. 1.

[0005] The conventional PDP includes a front glass substrate 1, serving as the display screen of the panel, having a back surface on which a plurality of row electrode pairs (X, Y), a dielectric layer 2 covering the row electrode pairs (X, Y), and an MgO-made protective layer 3 covering the back surface of the dielectric layer 2 are formed in this order.

[0006] Each of the row electrodes X (Y) includes transparent electrodes Xa (Ya) each formed of a wide transparent conductive film made of ITO (Indium Tin Oxide) or the like, and a bus electrode Xb (Yb) formed of a metal film of a small width assisting the conductivity of the transparent electrodes.

[0007] The row electrodes X and Y are arranged in alternate positions in the column direction such that the transparent electrodes Xa and Ya of the respective row electrodes X and Y face each other with a discharge gap g in between, and each of the row electrode pairs (X, Y) forms a display line L in matrix display.

[0008] The front glass substrate 1 is opposite a back glass substrate 4 with a discharge-gas-filled discharge space S in between. On the back glass substrate 4, a plurality of column electrodes D are regularly arranged and each extend in a direction at right angles to the row electrode pairs (X, Y); a column electrode protective layer 5 covers the column electrodes D; a partition wall 6 formed in a shape partitioning the discharge space as will be described later; and red-, green-, and blue-colored phosphor layers 7 individually formed in such a way as to cover the column electrode protective layer 5 and the side faces of the partition wall 6.

[0009] The partition wall 6 is formed in a grid shape of transverse walls 6A and vertical walls 6B. Each of the transverse walls 6A extends in a row direction in a position opposite the bus electrodes Xb and Yb which are arranged back to back in between the respective and adjacent row electrode pairs (X, Y). Each of the vertical walls 6B extends in a column direction in a position opposite a midpoint between the two adjacent transparent

electrodes Xa and between the two adjacent transparent electrodes Ya, the transparent electrodes Xa and Ya being lined up at regular intervals along the corresponding bus electrodes Xb and Yb of the respective row electrodes Y and X. The partition wall 6 defines discharge cells C in each of which the two transparent electrodes Xa and Ya of the row electrode pair (X, Y) face each other with the discharge gap g in between.

[0010] The partition wall 6 partitioning the discharge space into the discharge cells C is conventionally formed of insulating materials. For example, a thick coat of a partition wall material such as a glass paste or the like is applied on the back glass substrate 4 and then dried. Then, the resulting insulating materials undergo a sandblasting process through the medium of a mask, trimmed into a predetermined pattern, to be cut into the grid shape, and then a burning process for completion.

[0011] Such the foregoing conventional method of forming a partition wall is showed in JP Pat. Publication No. 2000-195431.

[0012] However, the conventional method of forming the partition wall with use of the sandblasting process has the problems of a degradation in productivity and an increase in manufacturing costs because of such a complicated manufacturing process.

[0013] Therefore, instead of the conventional partition wall formed by patterning the insulating materials, the use of metal-made partition wall covered with an insulating layer is suggested.

[0014] Fig. 3 is a plan view illustrating the structure of such a metal-made partition wall, and Fig. 4 is a side view illustrating the metal-made partition wall mounted on a substrate.

[0015] In Fig. 3, a metallic partition wall 10 having the surface covered with an insulating layer includes a portion 10A situated in a position corresponding to the display area of the display panel. The portion 10A has a matrix arrangement of through holes 10Aa opened therein and each having a quadrangular opening.

[0016] The display area portion 10A is surrounded by a flat plate-shaped portion 10B situated in a position corresponding to the non-display area of the display panel.

[0017] As shown in Fig. 4, the metallic partition wall 10 is arranged on the column electrode protective layer 5, covering the column electrodes on the back glass substrate 4 (see Fig. 2), so as to place each of the through holes 10Aa into a position for defining the corresponding discharge cell C.

[0018] After that, a burning process is performed so that the insulating layer of the metallic partition wall 10 is fused to the column electrode protective layer 5 to secure the metallic partition wall 10 onto the back glass substrate 4.

[0019] At this point, however, the following problems are produced in the metallic partition wall 10 structured as illustrated in Fig. 3.

[0020] During the burning process for securing the metallic partition wall 10 to the back glass substrate 4, in the

display area of the display panel, a binder (resin component) and the like evaporates from the column electrode protective layer 5 and then emanates from the through holes 10Aa of the metallic partition wall 10. However, the non-display area of the display panel has no escape route for the binder evaporating from the column electrode protective layer 5 and emanating from the non-display area portion 10B of the metallic partition 10 which is sited in the non-display area. As a result, after completion of the burning process, a difference in thickness is produced between the portion of the column electrode protective layer 5 corresponding to the display area of the display panel and the portion of the column electrode protective layer 5 corresponding to the non-display area.

[0021] Because of the this difference in thickness, thus, there may be occurrence of disjoining between the metallic partition wall 10 and the column electrode protective layer 5 in the boundary portion between the display area and the non-display area of the display panel.

[0022] A display panel and its manufacturing method according to the preambles of claims 1 and 5 is known from EP 448 727 A.

SUMMARY OF THE INVENTION

[0023] The present invention has been made to solve the problems associated with the display panels using the metallic partition wall as described above.

[0024] Accordingly it is an object of the present invention to prevent the occurrence of disjoining between a metallic partition wall and a column electrode protective layer in the boundary portion between a display area and a non-display area of a display panel.

[0025] An aspect of the present invention provides a display panel according to claim 1. The display panel includes: first and second substrates placed opposite each other to form a hermetically sealed space between them; a protective layer formed on the first substrate; and a metal plate which is covered with an insulating layer, and is fixed onto an inner surface of the first substrate by the resin layer, and has a plurality of unit-light-emission-area through holes formed in a matrix arrangement in a portion of the metal plate opposite a display area portion of the first substrate for formation of unit light emission areas, and burning-process-use through holes formed in a portion of the metal plate opposite a non-display area portion of the first substrate to function in a burning process.

[0026] In the manufacturing process for the display panel according to the first aspect, the metal plate having the unit-light-emission-areas through holes and the burning-process-use through holes is arranged in a predetermined position on the first substrate having the protective layer formed on its inner surface.

[0027] After that, the burning process is performed. Hence, the protective layer formed on the first substrate is fused to the insulating layer covering the metal plate, so that the metal plate is fixed to the predetermined po-

sition on the substrate concerned.

[0028] During the burning process, in the display area portion of the first substrate opposite the portion of the metal plate in which the unit-light-emission-area through holes are formed, a resin component evaporating from the protective layer formed on the first substrate emanates from the unit-light-emission-area through holes. Further, in the non-display area portion of the first substrate opposite the portion of the metal plate in which the burning-process-use through holes are formed, the resin component evaporating from the protective layer emanates also from the burning-process-use through holes.

[0029] Due to this design, in the display panel after the manufacturing process, the protective layer formed on the first substrate of the display panel has approximately equal thickness in the display area portion and the non-display area portion, and therefore has a negligible gap produced in the boundary portion between the display area portion and the non-display area portion.

[0030] As a result, with the display panel according to the first aspect of the present invention, it is possible to prevent the metal plate, constituting a partition wall for defining the unit light emission areas, from coming off from the substrate after completion of the manufacturing process.

[0031] A second aspect of the present invention provides a method of manufacturing display panels according to claim 5. The method includes the steps of: forming a protective layer on an inner surface of a first substrate of first and second substrates which will be placed opposite each other to form a hermetically sealed space between them; arranging, on the protective layer formed on the first substrate, a metal plate covered with an insulating layer and having a plurality of unit-light-emission-area through holes formed in a matrix arrangement in a portion opposite a display area portion of the first substrate for formation of unit light emission areas, and burning-process-use through holes formed in a portion opposite a non-display area portion of the first substrate to function in a burning process; and burning the first substrate, having the metal plate arranged thereon, to fix the metal plate onto the first substrate by the protective layer.

[0032] In the method of manufacturing the display panel according to the second aspect, the protective layer is formed on the inner surface of the first substrate, and then the metal plate with the unit-light-emission-areas through holes and the burning-process-use through holes is placed in a predetermined position on the first substrate with the protective layer.

[0033] After that, the burning process is performed. Hence, the protective layer formed on the first substrate is fused to the insulating layer covering the metal plate, so that the metal plate is fixed to the predetermined position on the first substrate.

[0034] During the burning process, in the display area portion of the first substrate opposite the portion of the metal plate in which the formed-for-unit-light-emission-area through holes are formed, a resin component evap-

orating from the protective layer formed on the first substrate emanates from the unit-light-emission-area through holes. Further, in the non-display area portion of the first substrate opposite the portion of the metal plate in which the burning-process-use through holes are formed, the resin component evaporating from the protective layer emanates from the burning-process-use through holes.

[0035] For this reason, the display panel manufactured by the method of manufacturing the display panels according to the present invention has the protective layer formed on the first substrate and having approximately equal thickness in the display area portion and the non-display area portion. Therefore the display panel has a negligible gap produced in the boundary portion between the display area portion and the non-display area portion of the resin layer.

[0036] As a result, the display panel manufactured by the method according to the present invention is capable of preventing the metal plate, constituting a partition wall for defining the unit light emission areas, from coming off from the substrate after completion of the manufacturing process.

[0037] These and other objects and features of the present invention will become more apparent from the following detailed description with reference to the accompanying drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

[0038]

Fig. 1 is a front view illustrating the structure of a conventional plasma display panel.

Fig. 2 is a sectional view taken along the V-V line in Fig. 1.

Fig. 3 is a plan view illustrating the structure of a conventional metallic partition wall.

Fig. 4 is a sectional view taken along the W-W line in Fig. 3.

Fig. 5 is a plan view illustrating an embodiment of a partition wall used in a displaypanel in accordance with the present invention.

Fig. 6 is a sectional view taken along the W1-W1 line in Fig. 5.

Fig. 7 is a plan view illustrating the structure of a back glass substrate of the plasma display panel.

Fig. 8 is a side view of the back glass substrate in Fig. 7.

Fig. 9 is a sectional side view illustrating the display-panel-use partition wall, shown in Fig. 5, mounted on the back glass substrate.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

[0039] Preferred embodiments according to the present invention will be described hereinafter in detail

with reference to the accompanying drawings.

[0040] Fig. 5 is a plan view illustrating an embodiment of the display panel according to the present invention. Fig. 6 a sectional view taken along the W1-W1 line in the display panel Fig. 5.

[0041] In Figs. 5 and 6, as in the case of the metallic partition wall 10 described in Fig. 3, a metallic partition wall 20 has a portion 20A located in the display area of the display panel. The portion 20A has a matrix arrangement of through holes 20Aa formed therein and each having a quadrangular-shaped opening.

[0042] A flat plate-shaped portion 20B located in the non-display area of the display panel is formed all around the display area portion 20A. A plurality of dummy through holes 20Ba is formed in the non-display area portion 20B.

[0043] In the embodiment, the dummy through hole 20Ba has a quadrangle shaped opening larger in size than that of the through hole 20Aa. The dummy through holes 20Ba are arranged at regular intervals in two rows in line with the display area portion 20A in each of the four side-margins of the non-display area portion 20B around the display area portion 20A of the metallic partition wall 20.

[0044] A registration through hole 20Bb is formed in each of the four corners of the non-display area portion 20B of the metallic partition wall 20.

[0045] As shown in Fig. 6, the entire surface of the metallic partition wall 20 is covered with an insulating layer 20a.

[0046] Next, a description will be given of a manufacturing process for mounting the metallic partition wall 20 on the back glass substrate for the manufacture of the display panel.

[0047] The following description takes as an example the manufacturing process for PDPs representative of the display panel. However, the metallic partition wall 20 according to the present invention is applicable to other flat display panels such as the FED and the like, and in this case, the manufacturing process is approximately the same as that for the PDP.

[0048] Fig. 7 is a plan view illustrating the structure of the back glass substrate of the PDP, and Fig. 8 is a sectional view of Fig. 7.

[0049] In Figs. 7 and 8, on the inner surface of the back glass substrate 4 (the upward surface in Fig. 8), column electrodes D each extending in a column direction (the up-down direction in Fig. 7) are arranged at regular intervals in a row direction (the right-left direction in Fig. 7).

[0050] The column electrodes D are covered with the column electrode protective layer 5 formed on the back glass substrate 4.

[0051] As will be described later, registration marks M are formed respectively in the four corners of the inner surface of the back glass substrate 4 in a one-to-one correspondence with the registration through holes 20Bb of the metallic partition wall 20.

[0052] In the manufacturing process, as illustrated in

Fig. 9, the metallic partition wall 20 is arranged on the back glass substrate 4 after the column electrodes D, the column electrode protective layer 5 and the registration marks M are formed as described earlier.

[0053] At this point, the metallic partition wall 20 is positionally adjusted with respect to the back glass substrate 4 such that the four registration through holes 20Bb formed in the four corners of the metallic partition wall 20 are respectively aligned with the four registration marks M formed in the four corners of the back glass substrate 4. Due to this positional adjustment, each of the through holes 20Aa of the metallic partition wall 20 is positioned to be in alignment with each intersection position between the column electrode D on the back glass substrate 4 and a row electrode pair formed on a front glass substrate when the back glass substrate 4 is joined on the front glass substrate in a later process.

[0054] After completion of the positional adjustment, a burning process is performed so that the column electrode protective layer 5 and the insulating layer 20a of the metallic partition wall 20 are fused to each other to fix the metallic partition wall 20 in the predetermined position on the back glass substrate 4.

[0055] At this point, in the display area portion 20A of the metallic partition wall 20, a binder (resin component) evaporating from the column electrode protective layer 5 during the burning process emanates from the through holes 20Aa formed in the display area portion 20A. And also in the non-display area portion 20B, the binder (resin component) evaporating from the column electrode protective layer 5 emanates from the dummy through holes 20Ba formed in the non-display area portion 20B.

[0056] For this reason, the display panel produced using the metallic partition wall 20 has the column electrode protective layer 5 of approximately equal thickness in the display area portion and the non-display area portion, which thus has a negligible chance of a gap occurring in the boundary portion between the display area portion and the non-display area portion.

[0057] As a result, the display panel produced using the metallic partition wall 20 is capable of preventing the metallic partition wall 20 from coming off from the back glass substrate 4 after completion of the manufacturing process.

[0058] A generic concept of the display panel according to the embodiment is a display panel including: first and second substrates placed opposite each other to form a hermetically sealed space between them; a protective layer formed on the first substrate; and a metal plate which is covered with an insulating layer, and is fixed to an inner surface of the first substrate with the protective layer, and has a plurality of unit-light-emission-area through holes formed in a matrix arrangement in a portion of the metal plate opposite a display area portion of the first substrate for formation of unit light emission areas, and burning-process-use through holes formed in a portion of the metal plate opposite a non-display area portion of the first substrate to function in a burning process.

ess.

[0059] In the manufacturing process for the display panel built on the generic concept, the metal plate having the unit-light-emission-areas through holes and the burning-process-use through holes is placed in a predetermined position on the first substrate having the protective layer formed on its inner surface.

[0060] After that, the burning process is performed. Hence, the protective layer formed on the first substrate is fused to the insulating layer covering the metal plate, so that the metal plate is fixed to the predetermined position on the first substrate concerned.

[0061] During the burning process, in the display area portion of the first substrate opposite the portion of the metal plate in which the unit-light-emission-area through holes are formed, a resin component evaporating from the protective layer formed on the first substrate emanates from the unit-light-emission-area through holes. Further, in the non-display area portion of the first substrate opposite the portion of the metal plate in which the burning-process-use through holes are formed, the resin component evaporating from the protective layer emanates from the burning-process-use through holes.

[0062] This design allows the resin layer formed on the first substrate of the display panel after the manufacturing process to have approximately equal thickness in the display area portion and the non-display area portion, and therefore the display panel has a negligible gap occurring in the boundary portion between the display area portion and the non-display area portion of the protective layer.

[0063] As a result, the display panel built on the generic concept is capable of preventing the metal plate, constituting a partition wall for defining the unit light emission areas, from coming off from the substrate after completion of the manufacturing process.

[0064] A generic concept of the method of manufacturing the display panel according to the embodiment includes the steps of: forming a protective layer on an inner surface of a first substrate of first and second substrates which will be arranged opposite each other to form a hermetically sealed space between them; arranging, on the protective layer formed on the first substrate, a metal plate covered with an insulating layer and having a plurality of unit-light-emission-area through holes formed in a matrix arrangement in a portion opposite a display area portion of the first substrate for formation of unit light emission areas, and burning-process-use through holes formed in a portion opposite a non-display area portion of the first substrate to function in a burning process; and burning the first substrate having the metal plate arranged thereon to secure the metal plate onto the first substrate by the protective layer.

[0065] In the manufacturing method for the display panel built on the generic concept, the protective layer is formed on the inner surface of the first substrate, and then the metal plate having the unit-light-emission-areas through holes and the burning-process-use through holes is arranged in a predetermined position on the first

substrate.

[0066] After that, the burning process is performed. Hence, the protective layer formed on the first substrate is fused to the insulating layer covering the metal plate, so that the metal plate is fixed to the predetermined position on the first substrate.

[0067] During the burning process, in the display area portion of the first substrate opposite the portion of the metal plate in which the unit-light-emission-area through holes are formed, a resin component evaporating from the protective layer formed on the first substrate emanates from the unit-light-emission-area through holes. Further, in the non-display area portion of the first substrate opposite the portion of the metal plate in which the burning-process-use through holes are formed, the resin component evaporating from the protective layer emanates from the burning-process-use through holes.

[0068] Accordingly, when the foregoing method is used for manufacturing display panels, the resulting display panel has the protective layer formed on the substrate in approximately equal thickness in the display area portion and the non-display area portion, and therefore has a negligible gap occurring in the boundary portion between the display area portion and the non-display area portion of the resin layer.

[0069] As a result, in the display panel manufactured by the method built on the generic concept, it is possible to prevent the metal plate, constituting a partition wall for defining the unit light emission areas, from coming off from the substrate after completion of the manufacturing process.

[0070] A generic concept of the partition wall used in the display panel according to the embodiment is a metal-made partition wall which: is placed between first and second substrates to partition a hermetically sealed space, formed between the two substrates, into unit light emission areas; has a plurality of formed-for-unit-light-emission-area through holes formed in a matrix arrangement in a portion of a metal plate opposite a display area portion of the first substrate for formation of the unit light emission areas, and burning-process-use through holes formed in a portion of the metal plate opposite a non-display area portion of the first substrate to function in a burning process; and has an outer surface entirely covered with an insulating layer.

[0071] In the manufacturing process for the display panel, the display-panel-use partition wall built on the generic concept is arranged in a predetermined position on the first substrate having the protective layer formed on its inner surface.

[0072] After that, the burning process is performed. Hence, the protective layer formed on the first substrate is fused to the insulating layer covering the display-panel-use partition wall, so that the display-panel-use partition wall is fixed to the predetermined position on the first substrate.

[0073] During the burning process, in the display area portion of the first substrate opposite the portion of the

display-panel-use partition wall in which the unit-light-emission-area through holes are formed, a resin component evaporating from the protective layer fused with the display-panel-use partition wall emanates from the unit-light-emission-area through holes. Further, in the non-display area portion of the first substrate opposite the portion of the display-panel-use partition wall in which the burning-process-use through holes are formed, the resin component evaporating from the protective layer emanates from the burning-process-use through holes.

[0074] Accordingly, in a display panel using the display-panel-use partition wall after the manufacturing process, the protective layer formed on the first substrate of the display panel has approximately equal thickness in the display area portion and the non-display area portion. Thus a gap occurring in the boundary portion between the display area portion and the non-display area portion of the resin layer is negligible.

[0075] As a result, once the display-panel-use partition wall built on the generic concept is fixed to the display panel, there may be no occurrence of disjoining between the display-panel-use partition wall and the substrate of the display panel.

[0076] The terms and description used herein are set forth by way of illustration only and are not meant as limitations. Those skilled in the art will recognize that numerous variations are possible within the scope of the invention as defined in the following claims.

Claims

1. A display panel comprising first and second substrates (1, 4) as well as a metal plate (20) located between the substrates (1, 4) and covered with an insulating layer (20a), wherein a hermetically sealed space is formed between the first and second substrates (1, 4) placed opposite to each other, and wherein a plurality of first through holes (20Aa) are formed in a matrix arrangement in a portion (20A) of the metal plate (20) opposite to a display area portion of the first substrate (4) for formation of unit light emission areas, **characterized in that** the metal plate (20) is fixed onto an inner surface of the first substrate (4) by a protective layer (5) formed on the first substrate (4), and **in that** second through holes (20Ba) are formed in a portion (20B) of the metal plate (20) opposite to a non-display area portion of the first substrate (4) for emanating substances in a burning process.
2. The display panel according to claim 1, **characterized in that** the second through holes (20Ba) are formed at regular intervals in the portion (20B) of the metal plate (20) opposite to the non-display area portion of the first substrate (4).

3. The display panel according to claim 1 or 2, **characterized in that** a registration mark (M) is indicated in a selected position on the inner surface of the first substrate (4), and a third through hole (20Bb) is formed in a portion of the metal plate (20) opposite to the registration mark (M) indicated on the first substrate (4). 5
4. The display panel according to claim 3, **characterized in that** a plurality of registration marks (M) are respectively indicated in a plurality of positions of the first substrate (4), and the third through holes (20Bb) are formed in the metal plate (20) in a number corresponding to the number of registration marks (M) indicated on the first substrate (4). 10
5. A method of manufacturing a display panel, comprising the following steps: 15
- forming a protective layer (5) on an inner surface of a first substrate (4) of two first and second substrates (1, 4) which are placed opposite to each other to form a hermetically sealed space between the first and second substrates (1, 4); 20
 - arranging, on the protective layer (5) formed on the first substrate (4), a metal plate (20) covered with an insulating layer (20a) and having a plurality of first through holes (20Aa) formed in a matrix arrangement in a portion (20A) opposite to a display area portion of the first substrate (4) for formation of unit light emission areas, and second through holes (20Ba) formed in a portion (20B) opposite to a non-display area portion of the first substrate (4) for emanating substances in a burning process; and 25
 - burning the first substrate (4) having the metal plate (20) arranged thereon, to fix the metal plate (20) onto the first substrate (4) by the protective layer (5). 30
6. The method according to claim 5, wherein in the step of arranging the metal plate (20) on the protective layer (5) formed on the first substrate (4), a position of a third through hole (20Bb) formed in the metal plate (20) and a position of a registration mark (M) formed in a selected position on the inner surface of the first substrate (4) are aligned with each other for registration of the metal plate (20) with respect to the first substrate (4). 35

Patentansprüche

1. Anzeigetafel, die folgendes aufweist: 55
- ein erstes und ein zweites Substrat (1, 4) sowie eine Metallplatte (20), die zwischen den Sub-

straten (1, 4) angeordnet ist und mit einer Isolierschicht (20a) bedeckt ist, wobei ein hermetisch abgedichteter Raum zwischen dem ersten und dem zweiten Substrat (1, 4) gebildet ist, die einander gegenüberliegend angeordnet sind, und wobei eine Vielzahl von ersten Durchgangsöffnungen (20Aa) in einer Matrixanordnung in einem Bereich (20A) der Metallplatte (20) gegenüber von einem Anzeigeflächenbereich des ersten Substrats (4) ausgebildet sind, um Lichtemissions-Flächeneinheiten zu bilden,

dadurch gekennzeichnet,

daß die Metallplatte (20) an einer inneren Oberfläche des ersten Substrats (4) mit einer auf dem ersten Substrat (4) ausgebildeten Schutzschicht (5) angebracht ist, und daß zweite Durchgangsöffnungen (20Ba) in einem Bereich (20B) der Metallplatte (20) gegenüber von einem Nicht-Anzeigeflächenbereich des ersten Substrats (4) ausgebildet sind, um Substanzen in einem Einbrennvorgang austreten zu lassen.

2. Anzeigetafel nach Anspruch 1, 25

dadurch gekennzeichnet,

daß die zweiten Durchgangsöffnungen (20Ba) in regelmäßigen Intervallen in dem Bereich (20B) der Metallplatte (20) gegenüber von dem Nicht-Anzeigeflächenbereich des ersten Substrats (4) gebildet sind. 30

3. Anzeigetafel nach Anspruch 1 oder 2, 35

dadurch gekennzeichnet,

daß eine Ausrichtmarkierung (M) in einer ausgewählten Position an der inneren Oberfläche des ersten Substrats (4) dargestellt ist und daß eine dritte Durchgangsöffnung (20Bb) in einem Bereich der Metallplatte (20) gegenüber von der an dem ersten Substrat (4) dargestellten Ausrichtmarkierung (M) gebildet ist. 40

4. Anzeigetafel nach Anspruch 3, 45

dadurch gekennzeichnet,

daß eine Vielzahl von Ausrichtmarkierungen (M) jeweils an mehreren Stellen des ersten Substrats (4) dargestellt sind und daß die dritten Durchgangsöffnungen (20Bb) in der Metallplatte (20) in einer Anzahl ausgebildet sind, die der Anzahl der an dem ersten Substrat (4) dargestellten Ausrichtmarkierungen (M) entspricht. 50

5. Verfahren zum Herstellen einer Anzeigetafel, wobei das Verfahren folgende Schritte aufweist:

- Bilden einer Schutzschicht (5) auf einer inneren Oberfläche eines ersten Substrats (4) von zwei Substraten (1, 4) mit einem ersten und einem zweiten Substrat, die einander gegenüberlie-

gend angeordnet sind, um einen hermetisch abgedichteten Raum zwischen dem ersten und dem zweiten Substrat (1, 4) zu bilden;

- auf der auf dem ersten Substrat (4) ausgebildeten Schutzschicht (5) wird eine Metallplatte (20) angeordnet, die mit einer Isolierschicht (20a) bedeckt ist und die eine Vielzahl von ersten Durchgangsöffnungen (20Aa) aufweist, die in einer Matrixanordnung in einem Bereich (20A) gegenüber von einem Anzeigeflächenbereich des ersten Substrats (4) gebildet sind, um Lichtemissions-Flächeneinheiten zu bilden, sowie zweite Durchgangsöffnungen (20Ba) aufweist, die in einem Bereich (20B) gegenüber von einem Nicht-Anzeigeflächenbereich des ersten Substrats (4) gebildet sind, um Substanzen in einem Einbrennvorgang austreten zu lassen; und

- Einbrennen des ersten Substrats (4), an dem die Metallplatte (20) angeordnet ist, um die Metallplatte (20) mit der Schutzschicht (5) an dem ersten Substrat (4) zu befestigen.

6. Verfahren nach Anspruch 5, wobei bei dem Schritt des Anordnens der Metallplatte (20) auf der auf dem ersten Substrat (4) ausgebildeten Schutzschicht (5) eine Position einer in der Metallplatte (20) ausgebildeten dritten Durchgangsöffnung (20Bb) und eine Position einer Ausrichtmarkierung (M), die in einer ausgewählten Position an der inneren Oberfläche des ersten Substrats (4) gebildet ist, zur Ausrichtung der Metallplatte (20) in bezug auf das erste Substrat (4) miteinander ausgefluchtet werden.

Revendications

1. Panneau d'affichage comprenant des premier et deuxième substrats (1, 4), ainsi qu'une plaque métallique (20) située entre les substrats (1, 4) et recouverte d'une couche isolante (20a),

- dans lequel un espace scellé hermétiquement est formé entre les premier et deuxième substrats (1, 4) placés opposés l'un à l'autre, et

- dans lequel une pluralité de premiers trous traversants (20Aa) est formée selon un agencement de matrice dans une partie (20A) de la plaque métallique (20) opposée à une partie de zone d'affichage du premier substrat (4) pour permettre la formation de zones d'émission de lumière unitaire,

caractérisé en ce que la plaque métallique (20) est fixée sur une surface interne du premier substrat (4) par une couche protectrice (5) formée sur le premier substrat (4), et **en ce que** des deuxièmes trous tra-

versants (20Ba) sont formés dans une partie (20B) de la plaque métallique (20) opposée à une partie de zone de non-affichage du premier substrat (4) pour faire sortir des substances au cours d'un procédé de cuisson.

2. Panneau d'affichage selon la revendication 1, **caractérisé en ce que** les deuxièmes trous traversants (20Ba) sont formés à intervalles réguliers dans la partie (20B) de la plaque métallique (20) opposée à la partie de zone de non-affichage du premier substrat (4).

3. Panneau d'affichage selon la revendication 1 ou 2, **caractérisé en ce qu'**un repère d'alignement (M) est indiqué dans une position sélectionnée sur la surface interne du premier substrat (4), et un troisième trou traversant (20Bb) est formé dans une partie de la plaque métallique (20) opposée au repère d'alignement (M) indiqué sur le premier substrat (4).

4. Panneau d'affichage selon la revendication 3, **caractérisé en ce qu'**une pluralité de repères d'alignement (M) est respectivement indiquée dans une pluralité de positions du premier substrat (4), et les troisièmes trous traversants (20Bb) sont formés dans la plaque métallique (20) selon un nombre correspondant au nombre de repères d'alignement (M) indiqué sur le premier substrat (4).

5. Procédé de fabrication d'un panneau d'affichage, comprenant des étapes consistant à :

- former une couche protectrice (5) sur une surface interne d'un premier substrat (4) de deux premier et deuxième substrats (1, 4) qui sont placés opposés l'un à l'autre pour former un espace scellé hermétiquement entre les premier et deuxième substrats (1, 4) ;

- agencer, sur la couche protectrice (5) formée sur le premier substrat (4), une plaque métallique (20) recouverte d'une couche isolante (20a) et ayant une pluralité de premiers trous traversants (20Aa) formée selon un agencement de matrice dans une partie (20A) opposée à une partie de zone d'affichage du premier substrat (4) pour permettre la formation de zones d'émission de lumière unitaire, et de deuxièmes trous traversants (20Ba) formée dans une partie (20B) opposée à une partie de zone de non-affichage du premier substrat (4) pour sortir des substances au cours d'un procédé de cuisson ; et

- cuire le premier substrat (4) sur lequel est agencée la plaque métallique (20), pour fixer la plaque métallique (20) sur le premier substrat (4) par la couche protectrice (5).

6. Procédé selon la revendication 5,
dans lequel au cours de l'étape consistant à agencer
la plaque métallique (20) sur la couche protectrice
(5) formée sur le premier substrat (4), une position
d'un troisième trou traversant (20Bb) formé dans la 5
plaque métallique (20) et une position d'un repère
d'alignement (M) formé dans une position sélection-
née sur la surface interne du premier substrat (4)
sont alignées l'une avec l'autre pour aligner la plaque
métallique (20) par rapport au premier substrat (4). 10

15

20

25

30

35

40

45

50

55

Fig.1

PRIOR ART

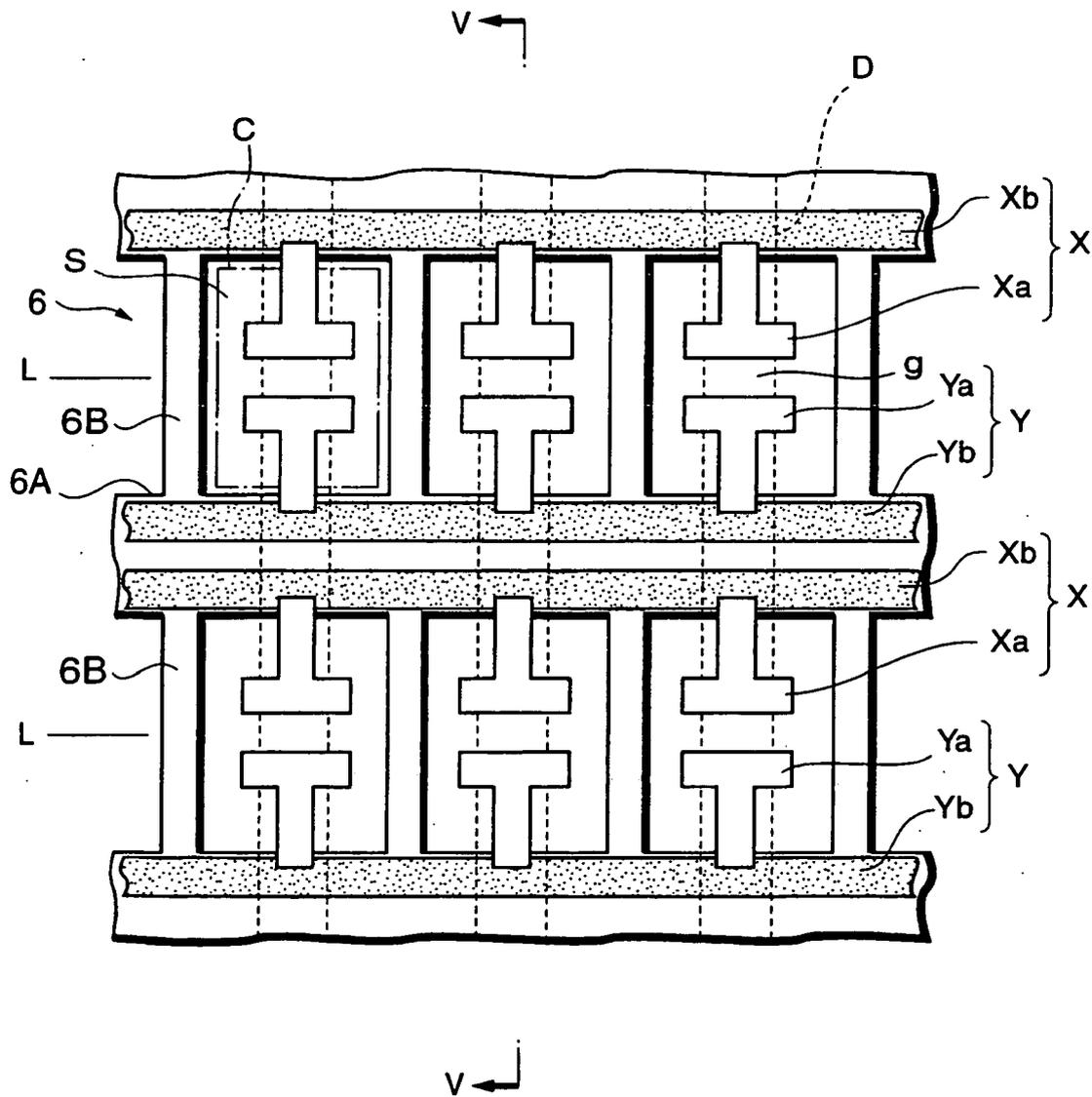


Fig.2

PRIOR ART

SECTION V-V

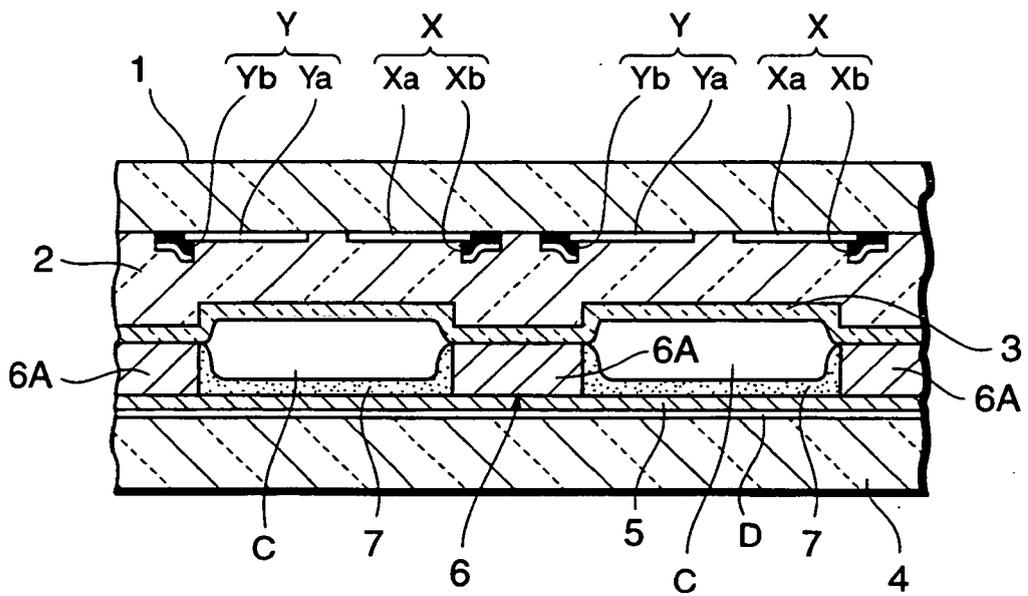


Fig.3

PRIOR ART

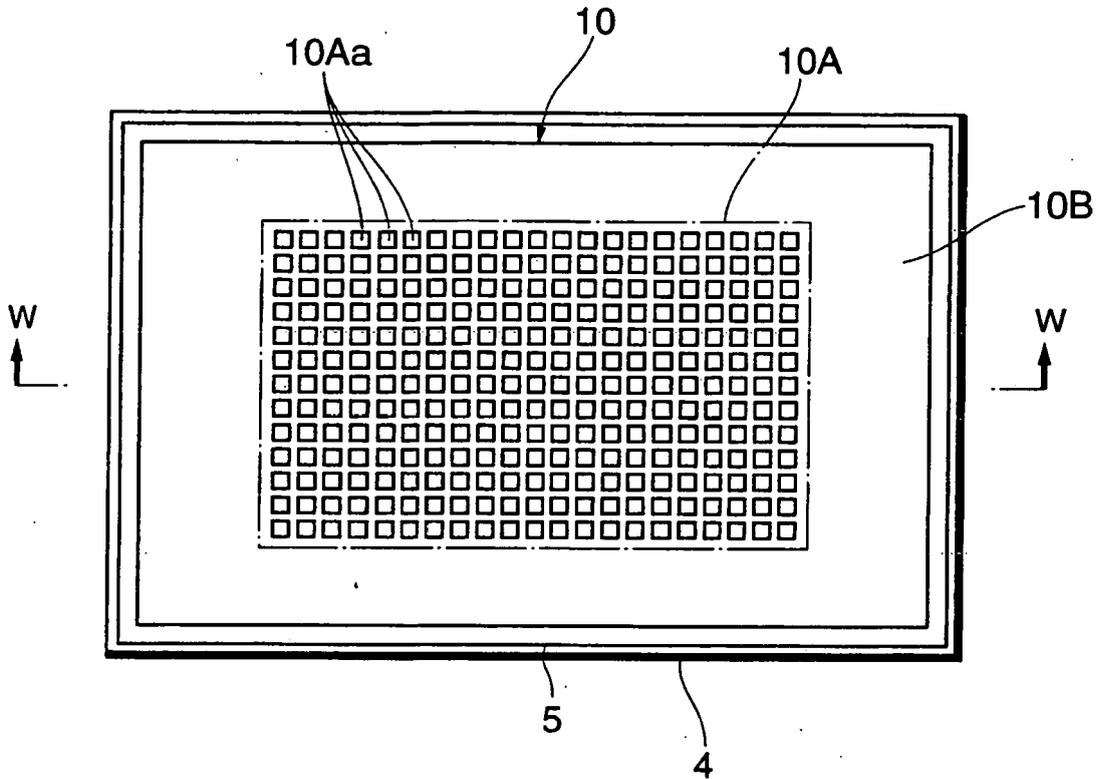


Fig.4

PRIOR ART

SECTION W-W

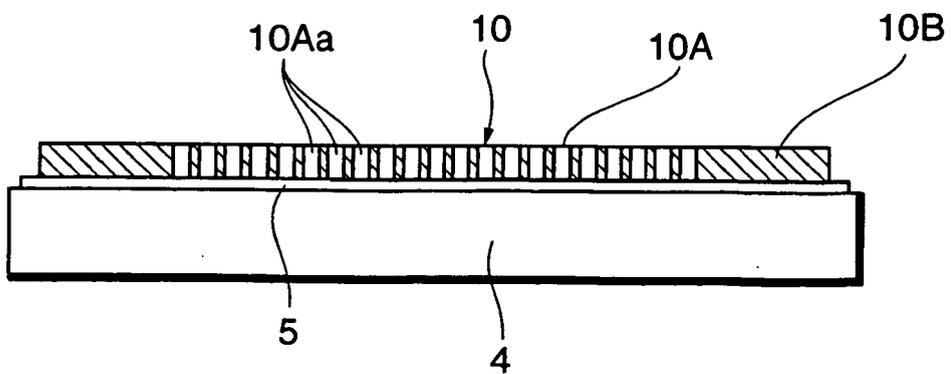


Fig.5

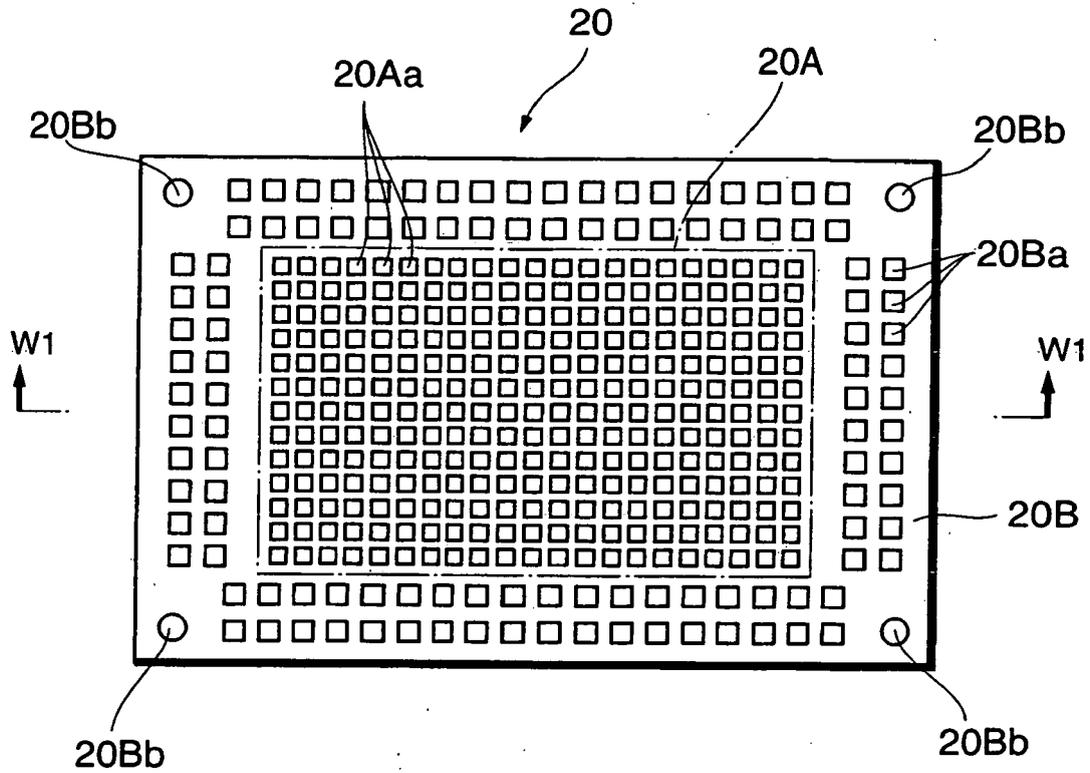


Fig.6

SECTION W1-W1

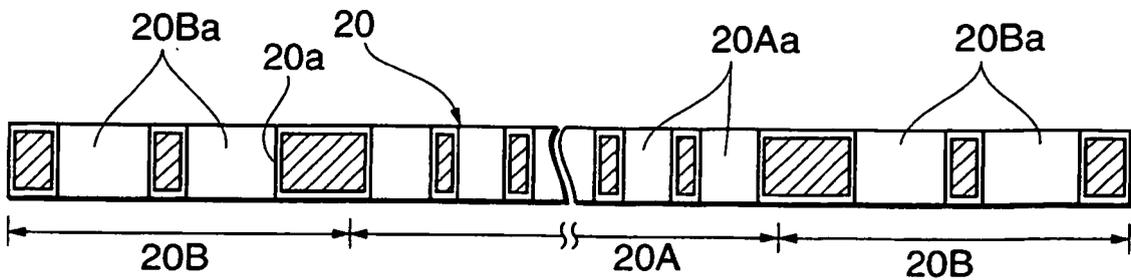


Fig.7

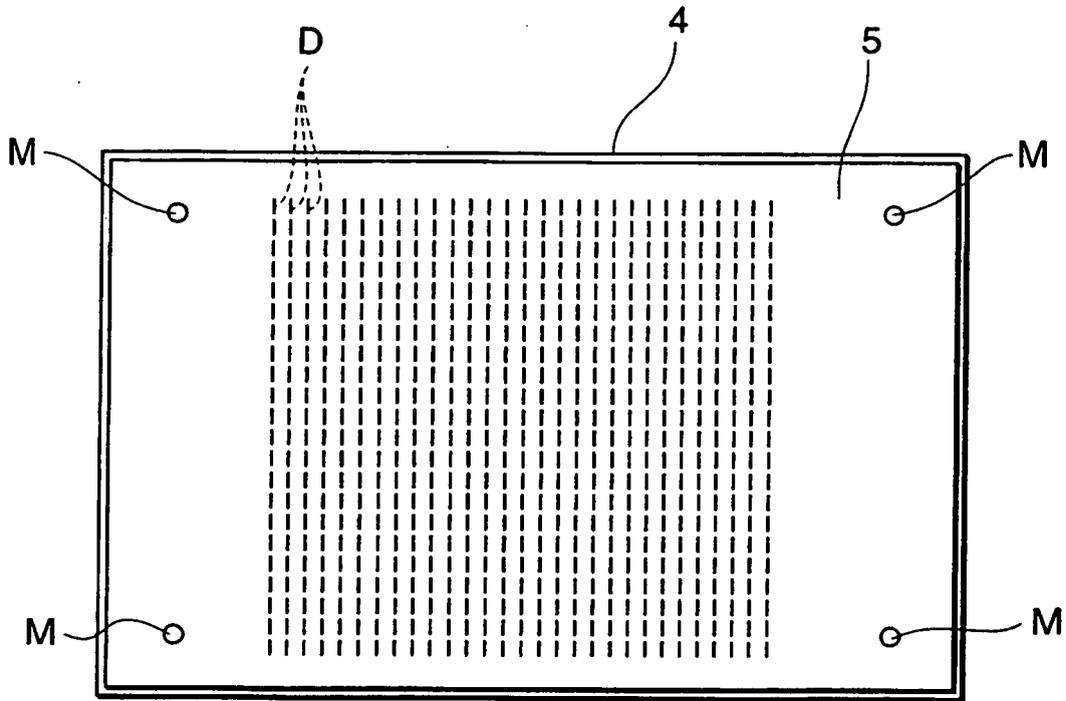


Fig.8

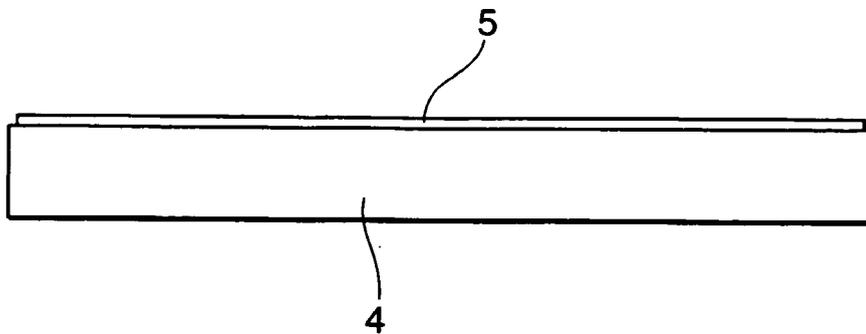
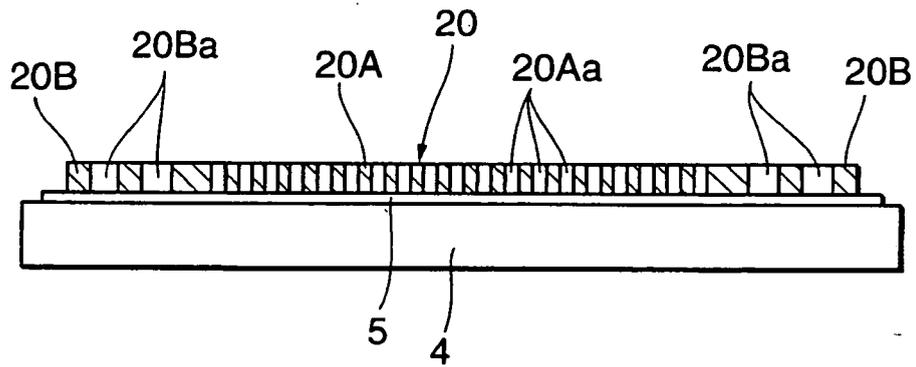


Fig.9



REFERENCES CITED IN THE DESCRIPTION

This list of references cited by the applicant is for the reader's convenience only. It does not form part of the European patent document. Even though great care has been taken in compiling the references, errors or omissions cannot be excluded and the EPO disclaims all liability in this regard.

Patent documents cited in the description

- JP 2002345727 A [0002]
- JP 2000195431 A [0011]
- EP 448727 A [0022]